# Small Outline Packages SOP



**Standard SOP** 

#### Suchi Semicon Offers

- Lead Count: 4,8,14,16,20,24,28
- o Lead Pitch : 1.27 mm
- Package Thickness : ~1.75mm
- $\circ$  MSL Level 1
- **o** Zero Delamination Process
- AECQ100/101 Qualification Options
- o ROHS Compliance



TSOP

### Suchi Semicon Offers

- Lead Count: 20 to 66 leads
- Lead Pitch : 0.5mm
- Package Thickness : ~1mm
- o MSL Level 1
- Zero Delamination Process
- AECQ100/101 Qualification Options
- ROHS Compliance



#### TSSOP

### Suchi Semicon Offers

- Lead Count: 8 to 48 leads
- o Lead Pitch : 0.5mm
- Package Thickness : less than 1mm
- o MSL Level 1
- Zero Delamination Process
- AECQ100/101 Qualification Options
- ROHS Compliance



### MSOP

## Suchi Semicon Offers

- Lead Count: 8.10,12, 16, 20 leads
- Lead Pitch: 0.65mm
- Package Thickness : less than 1mm
- o MSL Level 1
- Zero Delamination Process
- AECQ100/101 Qualification Options
- o ROHS Compliance